Power Transistors

NPN Silicon DPAK For Surface Mount Applications

Designed for high-gain audio amplifier applications.

Features

- High DC Current Gain
- Low Collector-Emitter Saturation Voltage
- High Current-Gain Bandwidth Product
- Epoxy Meets UL 94 V-0 @ 0.125 in
- NJV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free and are RoHS Compliant

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector-Base Voltage	V _{CB}	50	Vdc
Collector-Emitter Voltage	V _{CEO}	50	Vdc
Emitter-Base Voltage	V _{EB}	5	Vdc
Collector Current – Continuous	I _C	2	Adc
Collector Current - Peak	I _{CM}	3	Adc
Base Current	Ι _Β	0.4	Adc
Total Device Dissipation @ T _C = 25°C Derate above 25°C	P _D	15 0.1	W W/°C
Total Device Dissipation @ T _A = 25°C* Derate above 25°C	P _D	1.68 0.011	W W/°C
Operating and Storage Junction Temperature Range	T _J , T _{stg}	-65 to +175	°C
ESD - Human Body Model	HBM	3B	V
ESD - Machine Model	MM	С	V

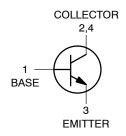
Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.



ON Semiconductor®

http://onsemi.com

SILICON POWER TRANSISTORS 2 AMPERES 50 VOLTS 15 WATTS





DPAK CASE 369C STYLE 1

MARKING DIAGRAM



A = Assembly Location

Y = Year WW = Work Week G = Pb-Free Device

ORDERING INFORMATION

Device	Package	Shipping [†]
NJD2873T4G	DPAK (Pb-Free)	2,500 Units / Reel
NJVNJD2873T4G	DPAK (Pb-Free)	2,500 Units / Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

1

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance Junction-to-Case Junction-to-Ambient (Note 1)	$R_{ hetaJC} \ R_{ hetaJA}$	10 89.3	°C/W

^{1.} These ratings are applicable when surface mounted on the minimum pad sizes recommended.

ELECTRICAL CHARACTERISTICS ($T_C = 25^{\circ}C$ unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
OFF CHARACTERISTICS				
Collector–Emitter Sustaining Voltage (Note 2) $(I_C = 10 \text{ mAdc}, I_B = 0)$	V _{CEO(sus)}	50	-	Vdc
Collector Cutoff Current $(V_{CB} = 50 \text{ Vdc}, I_E = 0)$	I _{CBO}	-	100	nAdc
Emitter Cutoff Current (V _{BE} = 5 Vdc, I _C = 0)	I _{EBO}	-	100	nAdc
ON CHARACTERISTICS	1			
DC Current Gain (Note 2) $ \begin{array}{l} (I_C = 0.5 \; A, \; V_{CE} = 2 \; V) \\ (I_C = 2 \; Adc, \; V_{CE} = 2 \; Vdc) \\ (I_C = 0.75 \; Adc, \; V_{CE} = 1.6 \; Vdc, \; -40 ^{\circ}C \leq T_J \leq 150 ^{\circ}C) \end{array} $	h _{FE}	120 40 80	360 - 360	-
Collector–Emitter Saturation Voltage (Note 2) (I _C = 1 A, I _B = 0.05 A)	V _{CE(sat)}	-	0.3	Vdc
Base-Emitter Saturation Voltage (Note 2) (I _C = 1 A, I _B = 0.05 Adc)	V _{BE(sat)}	-	1.2	Vdc
Base–Emitter On Voltage (Note 2) $ (I_C = 1 \text{ Adc, V}_{CE} = 2 \text{ Vdc}) \\ (I_C = 0.75 \text{ Adc, V}_{CE} = 1.6 \text{ Vdc, } -40^{\circ}\text{C} \leq \text{T}_\text{J} \leq 150^{\circ}\text{C}) $	V _{BE(on)}		1.2 0.95	Vdc
DYNAMIC CHARACTERISTICS	•			
Current-Gain - Bandwidth Product (Note 3) (I _C = 100 mAdc, V _{CE} = 10 Vdc, f _{test} = 10 MHz)	f⊤	65	-	MHz
Output Capacitance (V _{CB} = 10 Vdc, I _E = 0, f = 0.1 MHz)	C _{ob}	-	80	pF

^{2.} Pulse Test: Pulse Width = 300 $\mu s,$ Duty Cycle \approx 2%. 3. $f_T=\left|h_{fe}\right| \bullet f_{test}.$

TYPICAL CHARACTERISTICS

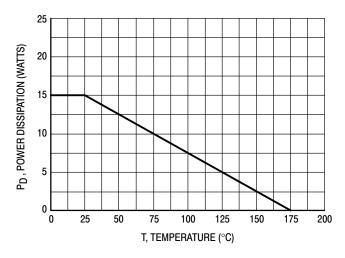


Figure 1. Power Derating

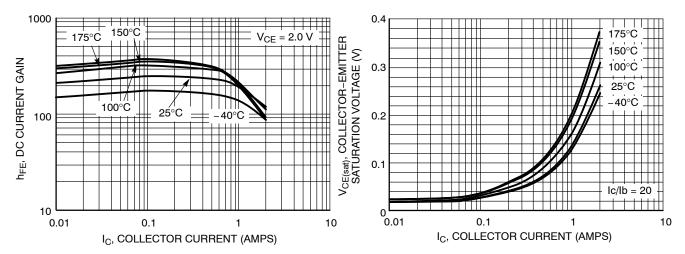


Figure 2. DC Current Gain

Figure 3. Collector-Emitter Saturation Voltage

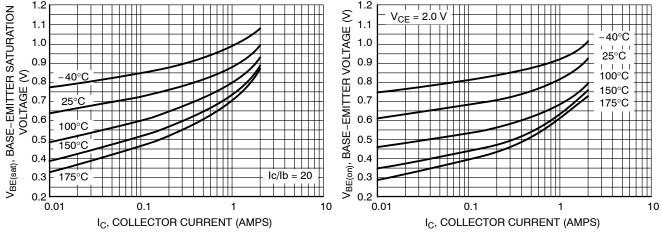
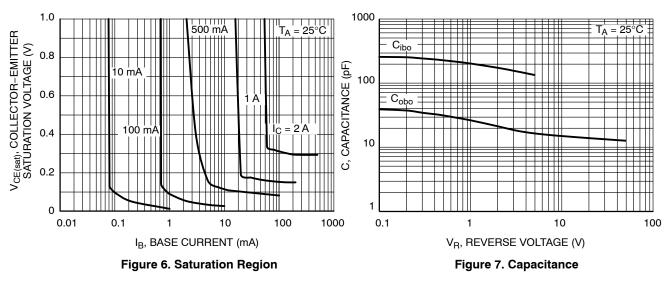


Figure 4. Base-Emitter Saturation Voltage

Figure 5. Base-Emitter Voltage



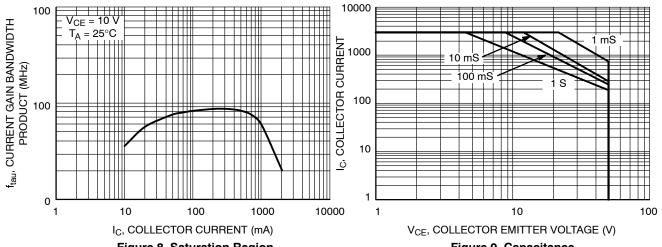


Figure 8. Saturation Region

Figure 9. Capacitance

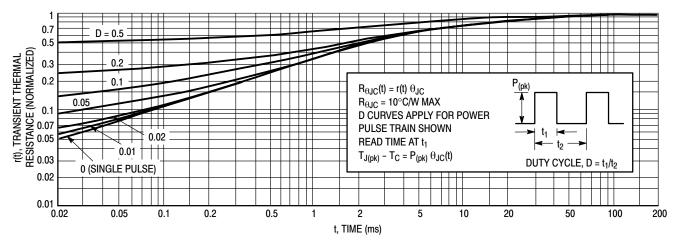
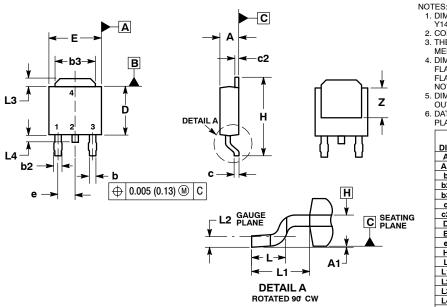


Figure 10. Thermal Response

PACKAGE DIMENSIONS

DPAK CASE 369C ISSUE D



- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- 2. CONTROLLING DIMENSION: INCHES.
 3. THERMAL PAD CONTOUR OPTIONAL WITHIN DI-
- MENSIONS b3, L3 and Z.
 4. DIMENSIONS D AND E DO NOT INCLUDE MOLD DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.006 INCHES PER SIDE. DIMENSIONS D AND E ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.
- DATUMS A AND B ARE DETERMINED AT DATUM

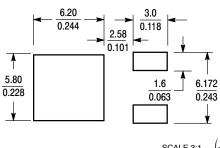
	INCHES		MILLIMETERS		
DIM	MIN	MAX	MIN	MAX	
Α	0.086	0.094	2.18	2.38	
A1	0.000	0.005	0.00	0.13	
b	0.025	0.035	0.63	0.89	
b2	0.030	0.045	0.76	1.14	
b3	0.180	0.215	4.57	5.46	
С	0.018	0.024	0.46	0.61	
c2	0.018	0.024	0.46	0.61	
D	0.235	0.245	5.97	6.22	
E	0.250	0.265	6.35	6.73	
е	0.090 BSC		2.29 BSC		
Н	0.370	0.410	9.40	10.41	
L	0.055	0.070	1.40	1.78	
L1	0.108 REF		2.74 REF		
L2	0.020 BSC		0.51 BSC		
L3	0.035	0.050	0.89	1.27	
L4		0.040		1.01	
Z	0.155		3.93		

STYLE 1: PIN 1. BASE 2. COLLECTOR

3.

EMITTER COLLECTOR

SOLDERING FOOTPRINT*



mm SCALE 3:1

ON Semiconductor and un are registered trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of SCILLC's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking, tadefined to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor P.O. Box 5163, Denver, Colorado 80217 USA **Phone**: 303–675–2175 or 800–344–3860 Toll Free USA/Canada **Fax**: 303–675–2176 or 800–344–3867 Toll Free USA/Canada

Email: orderlit@onsemi.com

N. American Technical Support: 800-282-9855 Toll Free USA/Canada

Europe, Middle East and Africa Technical Support: Phone: 421 33 790 2910 Japan Customer Focus Center

Phone: 81-3-5817-1050

ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative

^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.